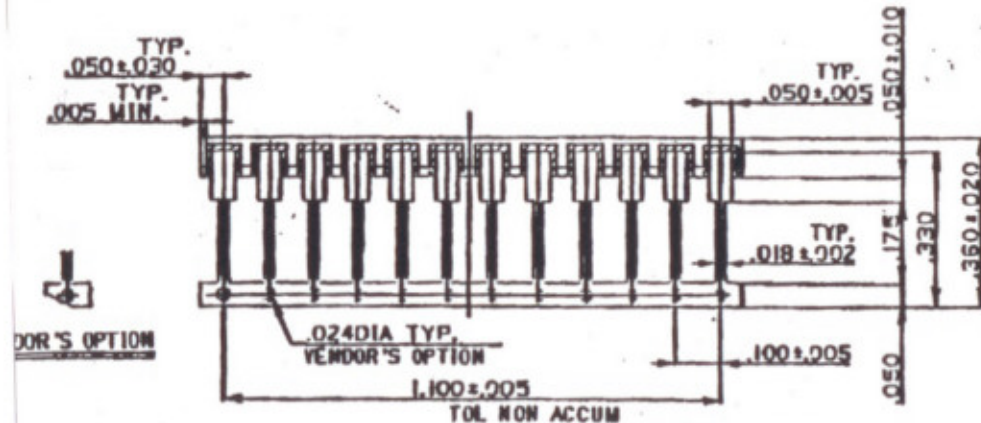


DETAIL-A

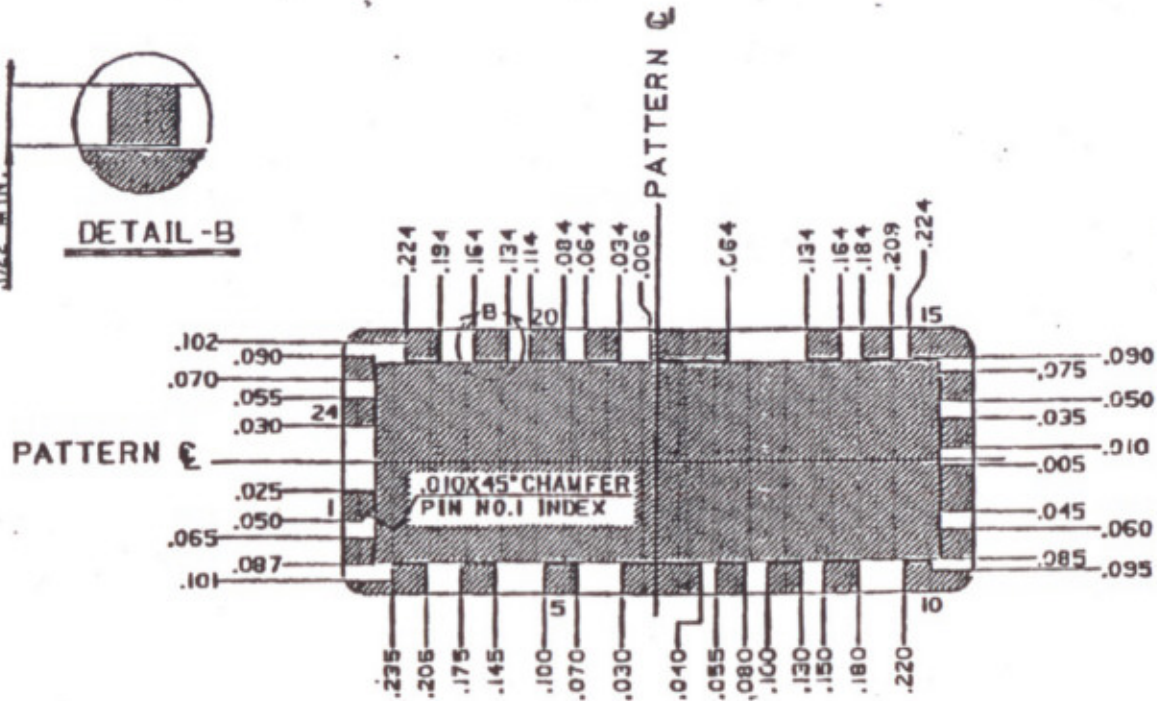
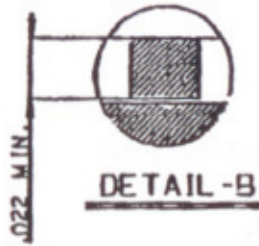


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.10 MAX. AT PIN NO. 10, 12, 14, 15, 16, 17, 24 OTHERS 0.30 MAX.

CSB02486-18-8

				NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
				24 LEAD SIDE BRAZED PACKAGE	±.005	M.K	K.O	K.M	OCT.07.86
				SCALE 5/1	MATERIAL AS INDICATED	<i>M. K. O.</i> DRAWING NO.			
CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	KD-S86927			SHEET 1/2





BONDING PATTERN

CHANGED	DATE	DRAWN	CHECKED	APPROVED	NAME	TOLENANCE	DRAWN	CHECKED	APPROVED	DATE
					24 LEAD SIDE BRAZED PACKAGE	MILS SQUARE PICKED	M.K	K.O	K.M	OCT.07.86
					SCALE 5/1	1				
						KYOCERA CORPORATION KYOTO JAPAN				DRAWING NO. KD-S86927
										SHEET 26

